AUTOMOTIVE GRADE

RoHS

COMPLIANT

HALOGEN

FREE



Vishay General Semiconductor

Surface-Mount TMBS® (Trench MOS Barrier Schottky) Rectifier

eSMP® Series



SMF (DO-219AB)

Cathode O Anode

Bottom view

LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS			
I _{F(AV)}	2.0 A		
V_{RRM}	200 V		
I _{FSM}	60 A		
V_F at $I_F = 2 \text{ A (T}_A = 125 °\text{C)}$	0.64 V		
T _J max.	175 °C		
Package	SMF (DO-219AB)		
Circuit configuration	Single		

FEATURES

- Trench MOS Schottky technology
- · Low profile package
- · Ideal for automated placement
- · Low forward voltage drop, low power losses
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- · Wave and reflow solderable
- AEC-Q101 qualified available Automotive ordering code: base P/NHM3
- Compatible to SOD-123W package case outline
- · Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

TYPICAL APPLICATIONS

For use in high frequency inverters, freewheeling, DC/DC converters, and polarity protection in commercial, industrial, and automotive applications.

MECHANICAL DATA

Case: SMF (DO-219AB)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant

Base P/NHM3_X - halogen-free, RoHS-compliant, and

AEC-Q101 qualified

("_X" denotes revision code e.g. A, B,....)

Terminals: matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meets JESD 201 class 2 whisker test

Polarity: color band denotes the cathode end

MAXIMUM RATINGS (T _A = 25 °C unless otherwise noted)				
PARAMETER	SYMBOL	V2F22	UNIT	
Device marking code		V2D		
Maximum repetitive peak reverse voltage	V _{RRM}	200	V	
Maximum DC reverse voltage	V _{DC}	160	V	
Maximum average forward rectified current (fig.1)	I _{F(AV)} (1)	2.0	A	
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I _{FSM}	60	А	
Operating junction temperature range	T _J ⁽²⁾	-40 to +175	°C	
Storage temperature range	T _{STG}	-55 to +175		

Notes

- (1) Free air, mounted on recommended copper pad area
- (2) The heat generated must be less than the thermal conductivity from junction-to-ambient: dPp/dTJ < 1/R_{6JA}



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ELECTRICAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	I _F = 1.0 A	- T _A = 25 °C		0.72	-	V
	$I_F = 2.0 \text{ A}$		V _F (1)	0.79	0.87	
	I _F = 1.0 A	- T _A = 125 °C	V _F (··/	0.56	-	
	I _F = 2.0 A			0.64	0.72	
Reverse current	V _R = 160 V	T _A = 25 °C		0.3	-	
	V _R = 100 V	T _A = 125 °C	I _B (2)	300	-	μA
	V _R = 200 V	T _A = 25 °C T _A = 125 °C	'R (-)	-	60	μΑ
	v _R = 200 v			700	3500	
Typical junction capacitance	4.0 V, 1 MHz		CJ	160	-	pF

Notes

(1) Pulse test: 300 µs pulse width, 1 % duty cycle

(2) Pulse test: Pulse width ≤ 5 ms

THERMAL CHARACTERISTICS (T _A = 25 °c unless otherwise noted)			
PARAMETER SYMBOL V2F22			
Typical thermal resistance	R ₀ JA (1)(2)	125	°C/W
	R _{0JM} (3)	26	C/VV

Notes

- $^{(1)}$ The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$
- $^{(2)}$ Free air, mounted on recommended copper pad area; thermal resistance $R_{\theta JA}$ junction to ambient
- $^{(3)}$ Mounted on recommended copper pad area; thermal resistance $R_{\theta JM}$ junction to mount

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
V2F22-M3/H	0.015	Н	3000	7" diameter plastic tape and reel
V2F22-M3/I	0.015	I	10 000	13" diameter plastic tape and reel
V2F22HM3_A/H (1)	0.015	Н	3000	7" diameter plastic tape and reel
V2F22HM3_A/I (1)	0.015	I	10 000	13" diameter plastic tape and reel

Note

(1) AEC-Q101 qualified



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RATINGS AND CHARACTERISTICS CURVES (T_A = 25 °C unless otherwise noted)

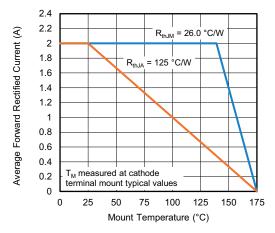


Fig. 1 - Maximum Forward Current Derating Curve

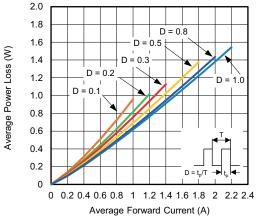


Fig. 2 - Average Power Loss Characteristics

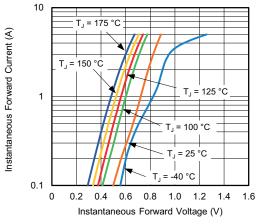


Fig. 3 - Typical Instantaneous Forward Characteristics

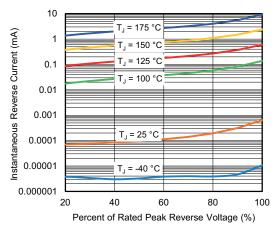


Fig. 4 - Typical Reverse Leakage Characteristics

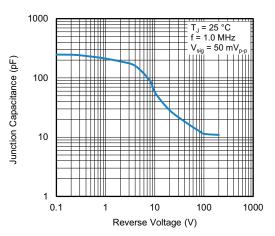


Fig. 5 - Typical Junction Capacitance

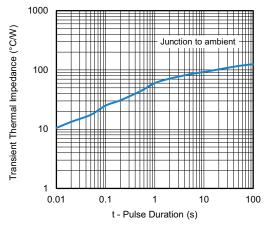
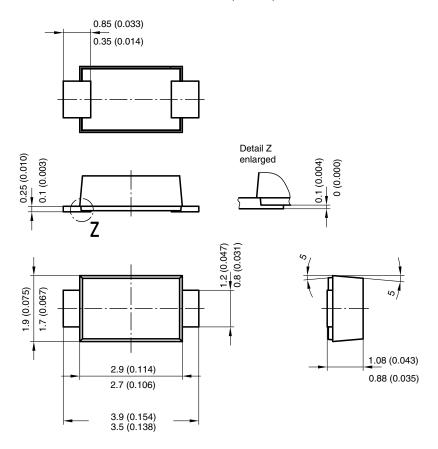


Fig. 6 - Typical Transient Thermal Impedance

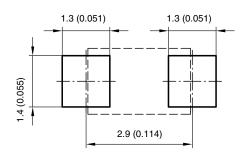


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PACKAGE OUTLINE DIMENSIONS in millimeters (inches)



Foot print recommendation:



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